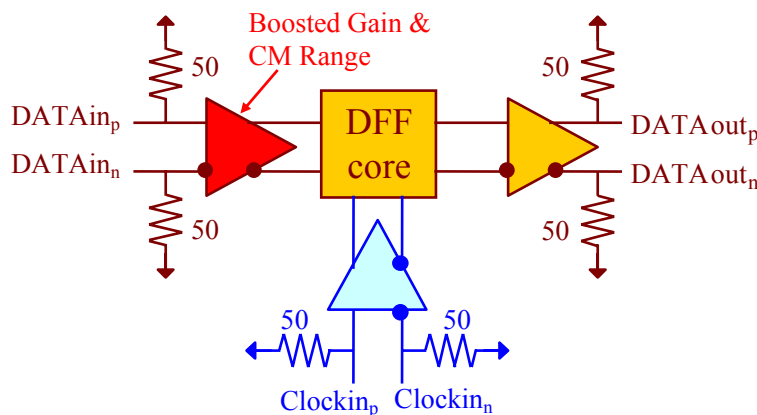


ASNT5012-KMC

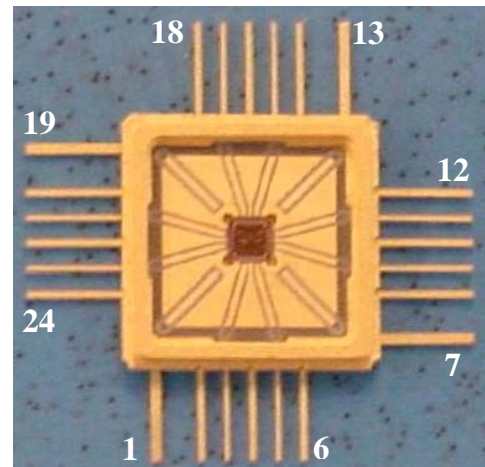
30Gbps D-Type Flip-Flop with Increased Input Signal Sensitivity

- High speed broadband D-Type Flip-Flop for data retiming with full rate clock.
- Sensitive input data buffer with increased CM range that is ideal for sampling applications.
- Exhibits low jitter and limited temperature variation over industrial temperature range.
- 30GHz analog input bandwidth for both clock and data.
- 6.5ps set-up/hold time capability.
- 87% clock phase margin for retiming of data input eye.
- Fully differential input and output buffers with on-chip 50Ω termination.
- CML output interface with 400mV single-ended swing.
- Single -3.3V power supply.
- Power consumption: 465mW.
- Fabricated in SiGe for high performance, yield, and reliability.
- Custom CQFP 24-pin package.

DESCRIPTION



Functional Block Diagram



Package View

The temperature stable ASNT5012-KMC SiGe IC provides broadband data retiming functionality and is intended for use in high-speed measurement / test equipment. ASNT5012-KMC can sample an up to 30Gbps data signal with an up to 30GHz clock source to create a 30Gbps retimed NRZ data output. The data input buffer is designed to have increased input signal sensitivity and is able to operate over a wider range of input common mode (CM) voltages. The part's I/Os support the CML logic interface with on chip 50Ω termination and may be used differentially, AC/DC coupled, single-ended, or in any combination. It operates from a single -3.3V power supply.



TERMINAL FUNCTIONS

| TERMINAL | | TYPE | DESCRIPTION |
|----------|---------------------------------|--------|---|
| NAME | (NO.) | | |
| vcc | 2,4,6,8,10,12 14-18,20,22,24 | PS | Power Supply: 0V (GND) |
| vee | 1,7,13,19 | PS | Power Supply: -3.3V |
| dp | 21 | Input | Differential CML high-speed data signal inputs |
| dn | 23 | | |
| cp | 3 | Input | Differential CML high-speed clock signal inputs |
| cn | 5 | | |
| outp | 11 | Output | Differential CML high-speed data signal outputs |
| outn | 9 | | |

ELECTRICAL CHARACTERISTICS

| PARAMETER | MIN | TYP | MAX | UNIT | COMMENTS |
|--------------------------|----------------------|----------------------|----------------------|------|--------------|
| VEE | -3.1 | -3.3 | -3.5 | V | ±6% |
| VCC | | 0.0 | | V | |
| IEE | | 140 | | mA | |
| Power | | 465 | | mW | |
| Junction Temp. | -25 | 50 | 125 | °C | |
| Input Data (d) | | | | | |
| Frequency | 0.0 | | 30 | Gbps | |
| CM Level | V _{cc} -1.5 | V _{cc} -0.3 | V _{cc} +0.3 | V | |
| SE Swing | 25 | 300 | 800 | mV | Peak-to-Peak |
| Input Clock (c) | | | | | |
| Frequency | 0.0 | | 30 | GHz | |
| CM Level | V _{cc} -0.8 | V _{cc} -0.3 | V _{cc} +0.3 | V | |
| SE Swing | 50 | 300 | 800 | mV | Peak-to-Peak |
| Duty Cycle | 40% | 50% | 60% | | |
| Output Data (out) | | | | | |
| Frequency | 0.0 | | 30 | Gbps | |
| CM Level | V _{cc} -0.3 | V _{cc} -0.2 | V _{cc} -0.1 | V | |
| SE Swing | 380 | 400 | 420 | mV | Peak-to-Peak |
| Rise/Fall Times | | | <13 | ps | 20%-80% |
| Additive Jitter | | | <2.5 | ps | Peak-to-Peak |
| Clock Phase Margin | 80% | 85% | 90% | | |

PACKAGE INFORMATION

The chip is packaged in ADSANTEC's custom 24-pin metal-ceramic package (CQFP). The package's mechanical information is available on the company's [website](#).